IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005, IPC.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						nd Mfg Iı	nformatio	n	
Supplier Infor	mation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Name			Title - Contact			I	Phone - Contact*				Em	Email - Contact*			
Product-Env-Stev	wards		Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com			
Authorized Repre	sentative*	Title - Representative			I	Phone - Representative*				Em	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com			
Reques	ester Item Number Mfr Iter		em Number Mfr Item Name				Effective Da	te Versio	n N	Manufacturing Site		Wei	Weight* UOM		Unit Type
		FAN3224TUMX-F085 Low-S		Low-Side Gate D	ow-Side Gate Driver SO8		2023-06-08 TH2		H2		80.7	80.792 mg		Each	
Ianufacturing	g Proccess Information	n										<u>'</u>			İ
Termina	Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MS	D-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Tempera		perature	ture Number of Reflow Cycles		cles
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 3		3		260		C	30	S	econds	3		
Comments															
TTENTION: MS	SL 3 Rated item requires Ba	ake and Dr	y Pack (after	electrical test)											
or more informa	tion regarding material con	nposition p	lease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.16	mg	Supplier	Silicon (Si)	7440-21-3		2.16	mg
Die Attach	1.144	mg	Supplier	Ethylene glycol dicyclopentenyl ether methacrylate	68586-19-6		0.04	mg
			Supplier	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3		0.0074	mg
			Supplier	Silver (Ag)	7440-22-4		1.0965	mg
Lead Frame	31.136	mg	Supplier	Zinc (Zn)	7440-66-6		0.0374	mg
			Supplier	Iron (Fe)	7439-89-6		0.7286	mg
			Supplier	Copper (Cu)	7440-50-8		30.3451	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0249	mg
Mold Compound-Black	45.29	mg		Epoxy resin	proprietary data		2.7174	mg
			Supplier	Phenolic Resin	Proprietary Data		2.7174	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2264	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.4965	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1322	mg
Plating	0.435	mg	Supplier	Palladium (Pd)	7440-05-3		0.0173	mg
			В	Nickel (Ni)	7440-02-0		0.4074	mg
			Supplier	Gold (Au)	7440-57-5		0.0104	mg
Wire Bond - Au	0.627	mg	Supplier	Gold (Au)	7440-57-5		0.627	mg